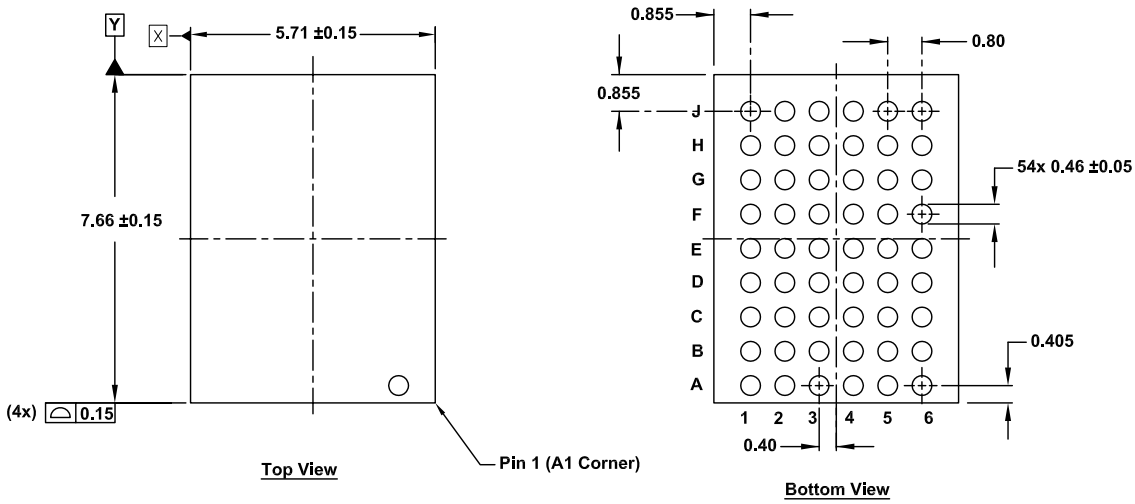
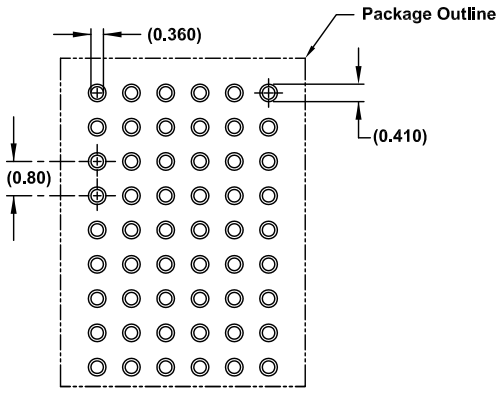
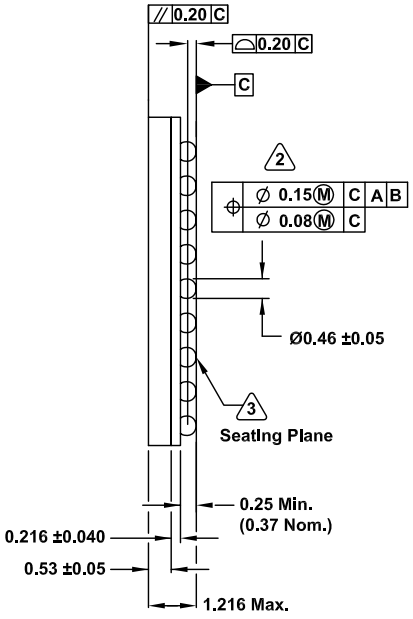
Package Outline Drawing

V54.5.71x7.66
54 Flip Chip Chip Scale Package (FCCSP)
Rev 3, 2/2022







Notes:

1. All dimensions and tolerances conform to ASME Y14.5 - 2009.
2. Dimension is measured at the maximum solder ball diameter, parallel to primary datum C.
3. Primary datum C and seating plane are defined by the spherical crowns of the solder balls.
4. Unless otherwise specified, dimensions are in millimeters.